

BM56 Series

0.35mm Pitch, 2.2mm Width, 0.6mm Stacking Height, Multi-RF Compatible FPC-to-Board Connector



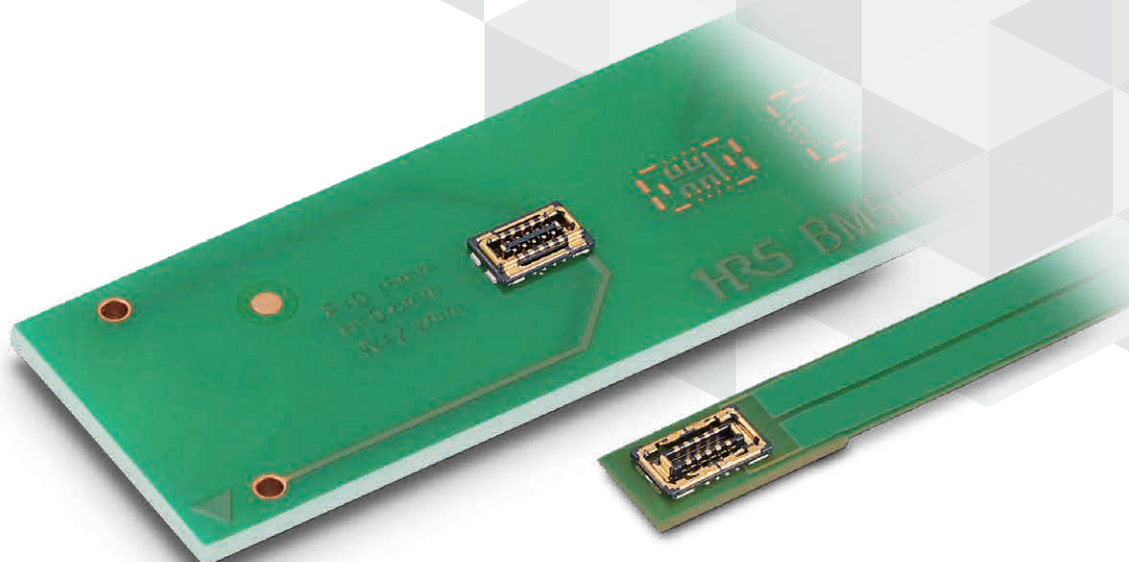
Multi-RF



EMI Prevention



Full Armored

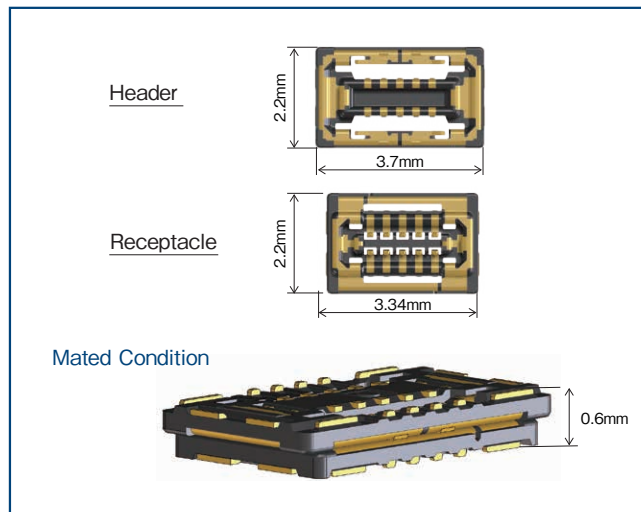


NEW

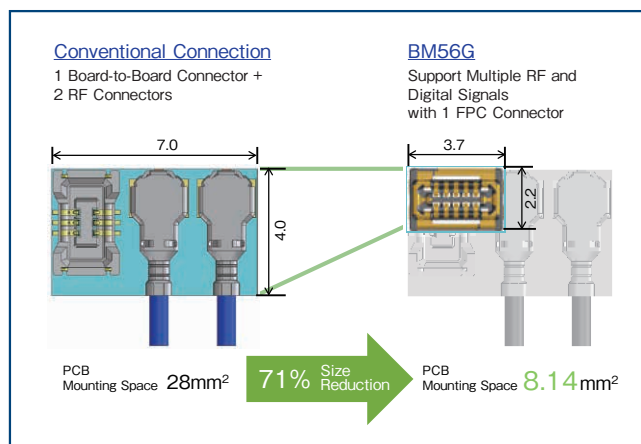
Features

1. Compact, Multi-RF capable FPC Connector, World's Smallest Width Class

Pitch : 0.35mm, Width: 2.2mm,
Stacking Height : 0.6mm



2. Contact Design Ideal for Both Digital and RF Signal



Digital and RF Signals Combined

3. Superior RF Signal Transmission

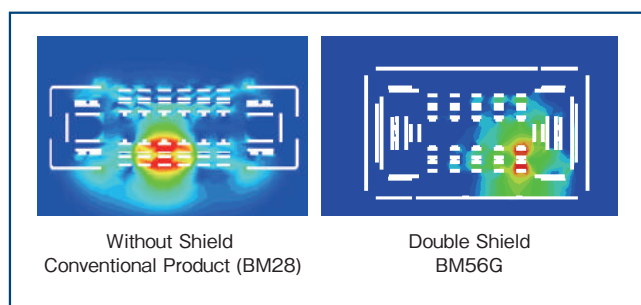
V.S.W.R.

DC to 1GHz : 1.2 Max.

1 to 6GHz : 1.3 Max.

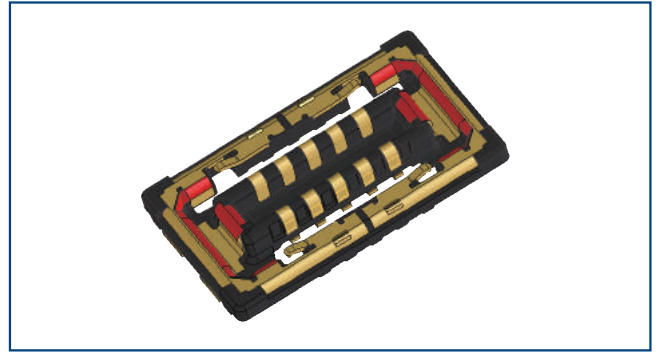
6 to 20GHz : 1.5 Max

4. Double Shield Enhances EMI Prevention



Good EMI Resistance

5. Robust Mating Guides



Metal Guide Design

6. Halogen-free

No chlorine or bromine exceeding the standard values are used in this connector.

In accordance with IEC 61249-2-21

Br : 900ppm max, Cl : 900ppm max, Br+Cl : 1500ppm max

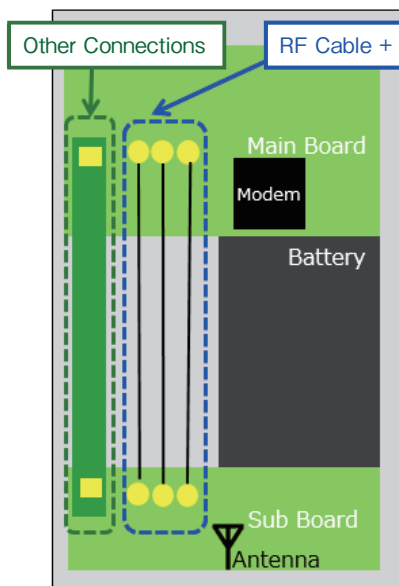
Applications

Devices that require low-profile, compact design such as smartphones, wearable terminals and tablet PCs.

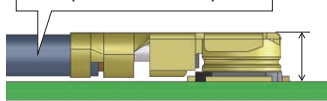
Conventional Internal Connection

RF Connection: RF Cable + RF Connector

Other Connections: FPC + Board-to-Board Connector

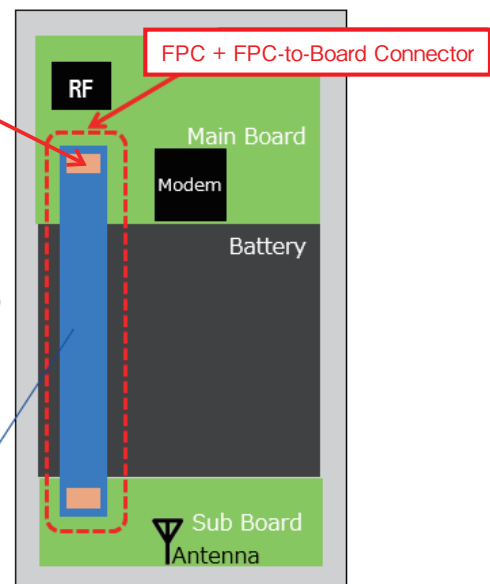


No space for other parts



New Connection Proposal

Connect RF and Other Signals with FPC and FPC-to-Board Connector

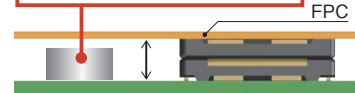


BM56G

Integrating FPC and FPC-to-Board

FPC can be placed on top of the battery

Other parts can be mounted



Product Specifications

Rated Current	Signal Contact : 1.0A	Operating Temperature (Note 1)	-55 to + 85℃
Rated Voltage	30V AC/DC	Operating Humidity Range (Note 2)	90% RH Max.
		Storage Temperature Range (Note 3)	-10 to + 60℃
		Storage Humidity Range (Note 2)(Note 3)	90% RH Max.

Characteristic Impedance	50 Ω	Rated Frequency	DC to 20GHz
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Items	Specifications	Conditions
Contact Resistance	Signal Contact 50m Ω Max.	Measured at 20mV AC, 1kHz, and 1mA
Insulation Resistance	100 MΩ Min.	Measured at 100V DC
Withstanding Voltage	No flashover or dielectric breakdown	150V AC for 1 min.
Mating Durability	Signal Contact 50m Ω Max.	10 cycles
Vibration Resistance	No electrical discontinuity of 1 μ s or more.	Frequency : 10 to 55Hz ; half amplitude of 0.75mm,10 cycles in each of 3 axis directions for 5 minutes/cycle, 10 cycles each, 30 cycles total
Shock Resistance	No electrical discontinuity of 1 μ s or more.	Acceleration : 450m/s ² , duration : 11ms, 3-axis half sine wave in 3 directions, 3 cycles for each
Humidity Resistance	Signal Contact : 50m Ω Max. Insulation Resistance : 50M Ω Min.	Left for 96 hours at a temperature of 40 ± 2℃ and a humidity range from 90 to 95%
Temperature Cycle	Signal Contact : 50m Ω Max. Insulation Resistance : 50M Ω Min.	-55℃ for 30 minutes → +85 for 30 minutes, 5 cycles
Solder Heat Resistance	No dissolution or resin melting that will affect performance.	Reflow : At recommended temperature profile Hand solde : Solder iron temperature of 350℃ for 3 seconds Max.
V.S.W.R.	DC to 1GHz : 1.2 Max. 1 to 6GHz : 1.3 Max. 6 to 20GHz : 1.5 Max	

Note 1 : Includes temperature rise caused by current flow.

Note 2 : Use without condensation.

Note 3 : Storage refers to long-term storage of unused items before they are mounted on the PCB.

Operating temperature and humidity range apply when the product is not powered after PCB mounting and when temporarily stored during transportation.

Materials / Finish

Part	Component	Materials	Finish	UL Standard
Header Receptacle	Insulator	LCP	Black	UL94V-0
	Contact	Copper Alloy	Gold Plated	-
	Shield	Copper Alloy	Gold Plated	-

Product Number Structure

Refer to the chart below when determining the product specifications from the product number.
Please select from the product numbers listed in this catalog when placing orders.

●Header/Receptacle

BM56G - 10 DP - 0.35 V (##)

1

2

3

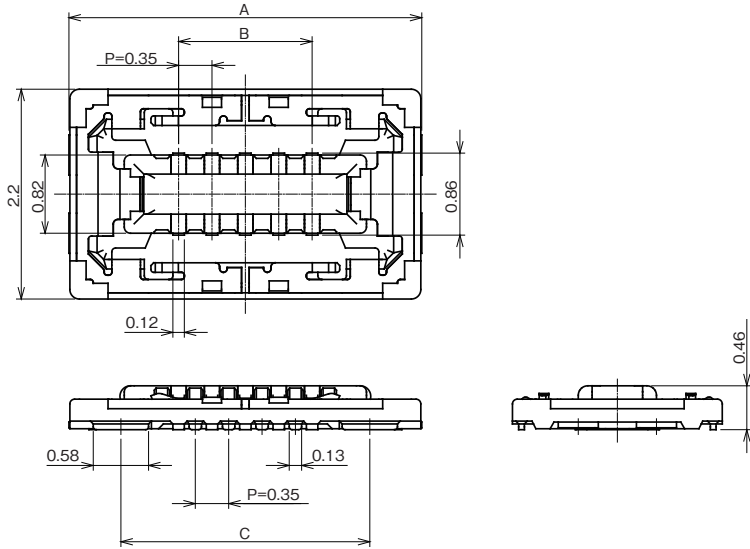
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5

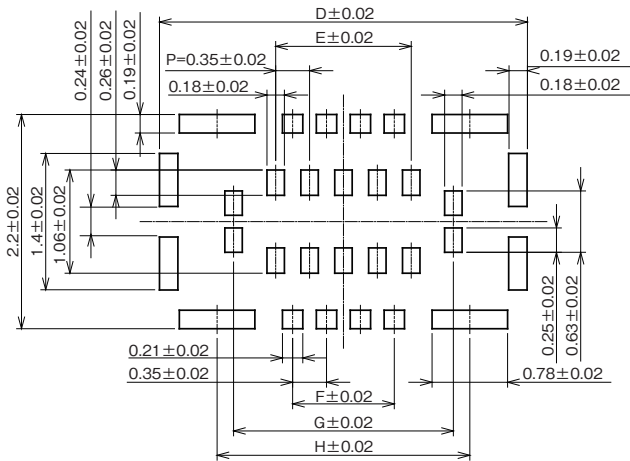
6

1 Series Name	BM56G	4 Contact Pitch	0.35mm
2 No. of Signal Contacts	10	5 Terminal Design	V : Straight SMT
3 Connector Type	DP : Header DS : Receptacle	6 Plating Specifications and Packaging	(51) : Standard, Embossed Packaging (20,000pcs per reel) (53) : Embossed Packaging (1,000pcs per reel)

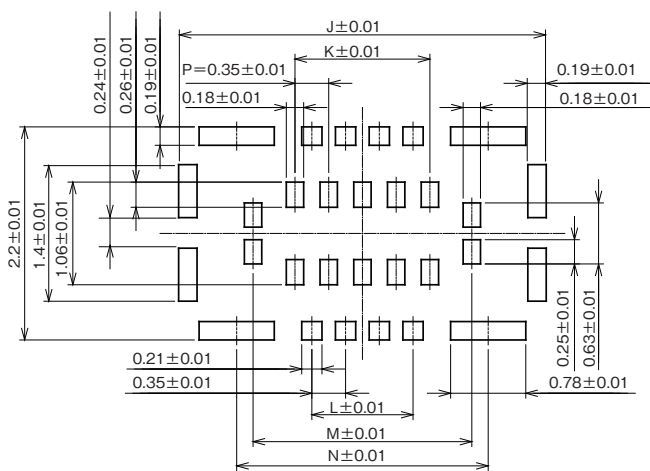
Header



Recommended PCB Layout



Recommended Metal Mask Dimensions
(Mask Thickness : 0.08mm)

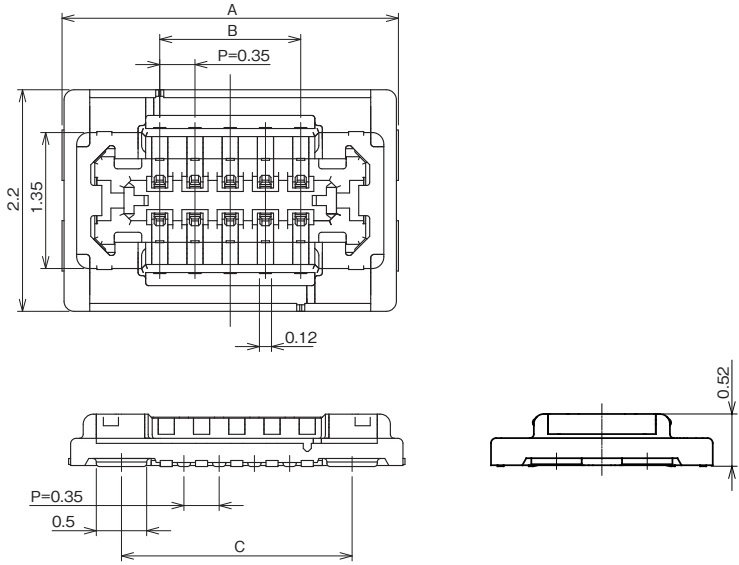


Unit : mm

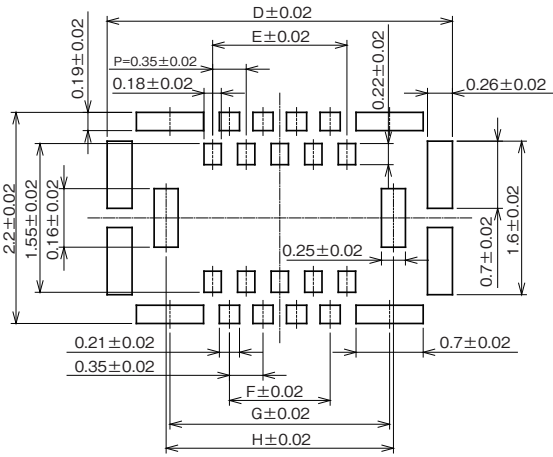
Part No.	HRS No.	No. of Pos.	A	B	C	D	E	F	G	Purchase Unit	
										(##) : (51)	(##) : (53)
BM56G-10DP-0.35V(##)	CL0673-7500-0-##	10	3.7	1.4	2.61	3.8	1.4	1.05	2.27	20,000pcs per reel	1,000pcs per reel
			H	J	K	L	M	N			
			2.61	3.8	1.4	1.05	2.27	2.61			

Note : This connector has no polarity.

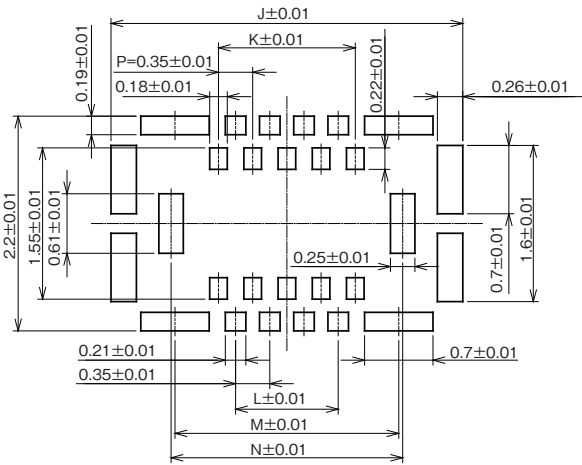
Receptacle



● Recommended PCB Layout



● Recommended Metal Mask Dimensions
(Mask Thickness : 0.08mm)



Unit : mm

Part No.	HRS No.	No. of Pos.	A	B	C	D	E	F	G	Purchase Unit	
										(##) : (51)	(##) : (53)
BM56G-10DS-0.35V(##)	CL0673-7501-0-##	10	3.34	1.4	2.29	3.6	1.4	1.05	2.29	20,000pcs per reel	1,000pcs per reel
			H	J	K	L	M	N			
			2.37	3.6	1.4	1.05	2.29	2.37			

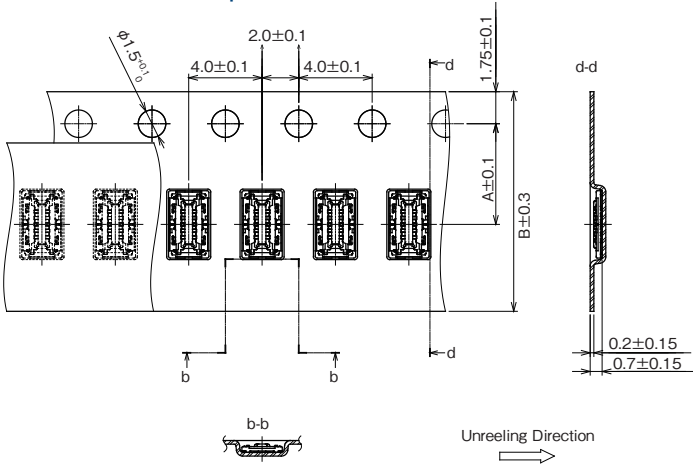
Note : This connector has no polarity.

Packaging Specifications Diagram

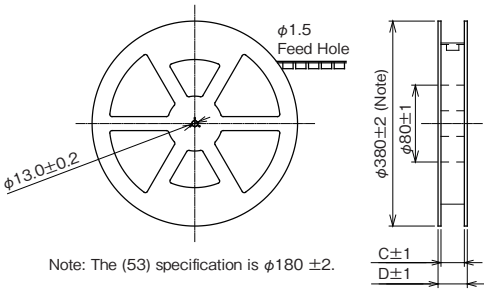
IEC 60286-3, JIS C 0806 Compliant

Header

●Embossed Tape Dimensions



●Reel Dimensions

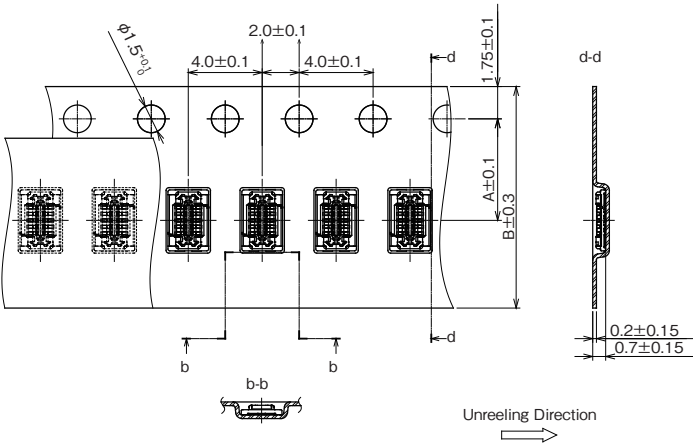


Unit : mm

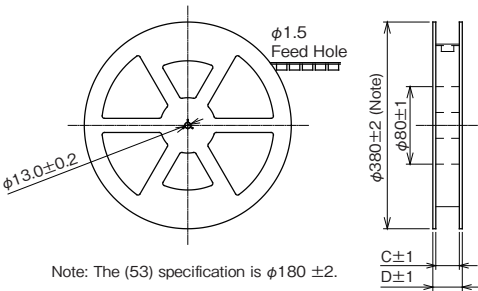
Part No.	No. of Pos.	A	B	C	D
BM56G-10DP-0.35V(##)	10	5.5	12.0	13.4	17.4

Receptacle

●Embossed Tape Dimensions



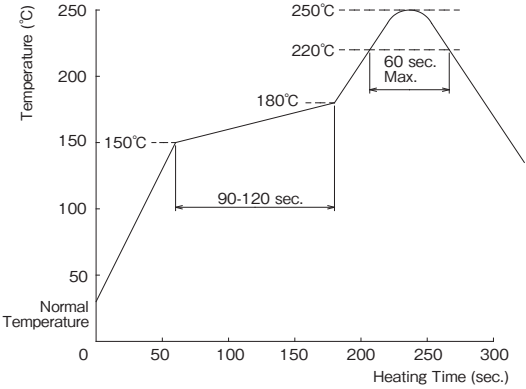
●Reel Dimensions



Unit : mm

Part No.	No. of Pos.	A	B	C	D
BM56G-10DS-0.35V(##)	10	5.5	12.0	13.4	17.4

Usage Precautions

Recommended Temperature Profile	 【Conditions】 1. Peak Temperature : 250°C 2. Heating : 220°C min. for 60 sec. max. 3. Preheating : 150 to 180°C, 90 to 120 sec. 4. Number of Reflow Cycles : 2 cycles max. Note 1 : Temperature refers to the surface temperature of the board near the connector lead. Note 2 : When using nitrogen reflow, oxygen concentration must be 1000 [ppm] or more for mounting. If it is less than 1000 [ppm], please contact a Hirose representative.
Recommended Manual Soldering Conditions	Soldering iron temperature : $340 \pm 10^{\circ}\text{C}$; Soldering time : within 3 seconds
Recommended Metal Mask Thickness and Open Area to PCB Pattern Area Ratio	Thickness : 0.08mm Aperture Ratio : Header Side : 100%, Receptacle Side : 100%
Board Warpage	Max. of 0.02mm at the center in reference to both ends of the connector
Cleaning	Cleaning is not recommended. If you clean this product, please evaluate its performance before using it. (Cleaning may impair the mating/unmating properties and lower resistance to environmental factors.)
Precautions	• Be careful when mating/unmating the connector when it is not mounted on the PCB as it may cause damage/deformation to contacts. • Avoid supporting the PCB only with the connectors. Support it by other means such as bolts, screws, posts, etc. • Excessive prying during unmating/mating may result in damage. • In the case of hand soldering, please do not apply any flux which could cause flux wicking. • This product may have slight color differences due to production lot variability, but this does not affect the performance. • Please refer to the following page for handling precautions when inserting and removing. • Because the product can disengage if dropped (or other impact), or by FPC routing, it is advised to secure the mated connectors to the board with housings and cushioning materials. • Do not use the connector in non-recommended conditions (i.e., rated current, rated voltage, PCB design and operating environment, etc.). Such usage could lead to material outgassing, ignition, or short-circuit, etc. Refer to the specifications and guidelines for board pattern dimensions, board cautions, and connector treatment. Please contact Hirose if connector usage in conditions other than those described in the specifications and the guidelines is being considered.

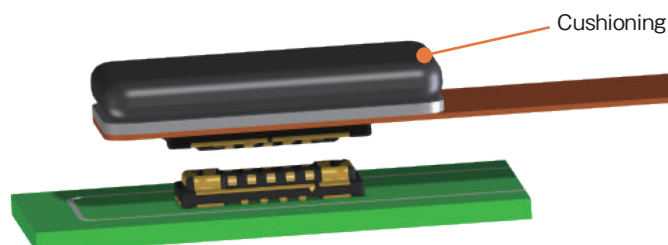
Connector Handling Precautions

【Mating Disengagement Prevention】

Please use cushioning.

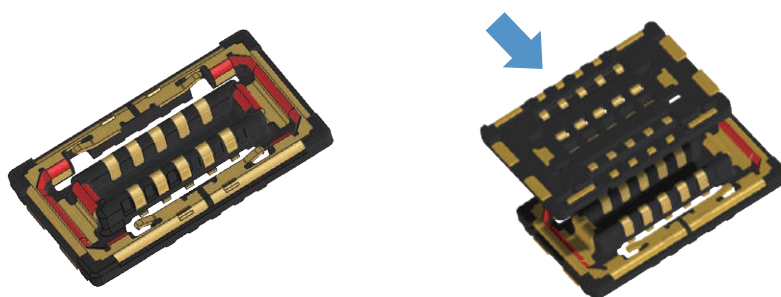
This connector may come off due to impact such as dropping.

Cushioning should be large enough to cover the entire connector.

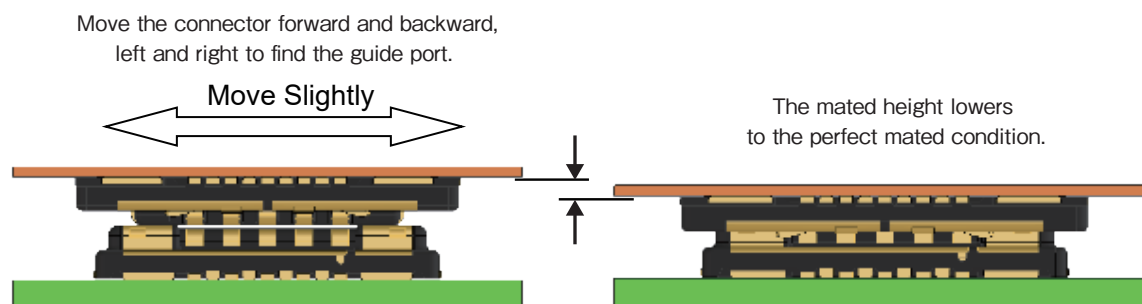


【Mating Method】

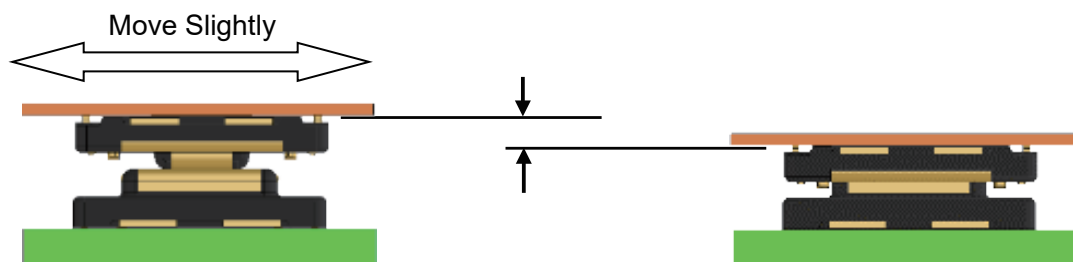
1. Locate the guide port and align. This product has a guide rib on the header to ensure proper engagement. Align the connector so that it is in this position.



2. Once aligned, the connector engages. You can feel the mated height of the connector lower.



3. In the engaged state, the connectors are parallel to each other, and the connectors cannot move forward, backward, left, or right. Complete mating from this state.

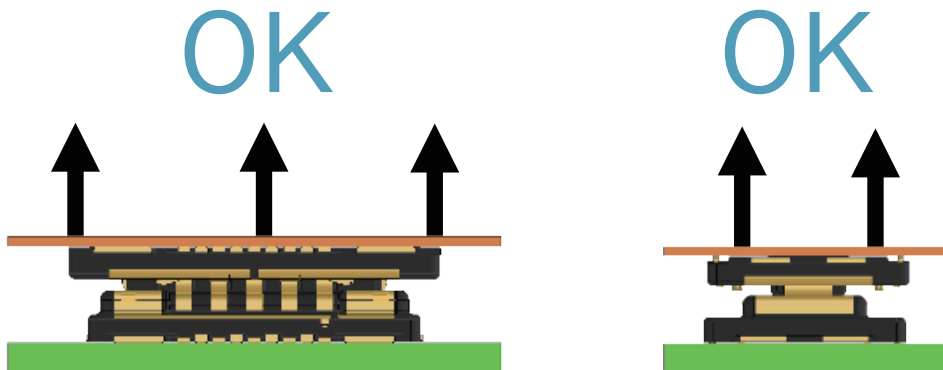


4. Check that mating is completed.
If one side is floating, or if it is mated at a diagonal, remove and re-mate.

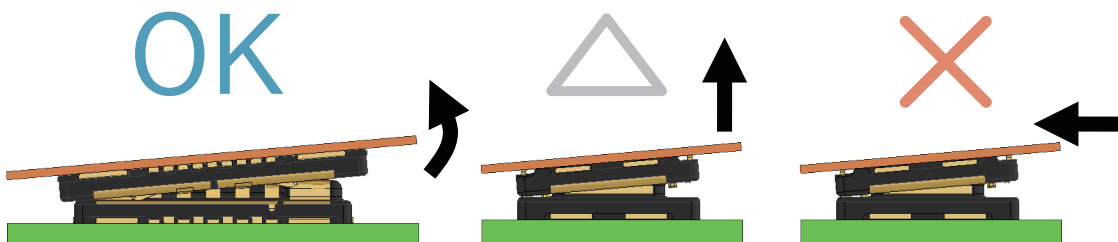


【Handling Precautions for Connector Removal】

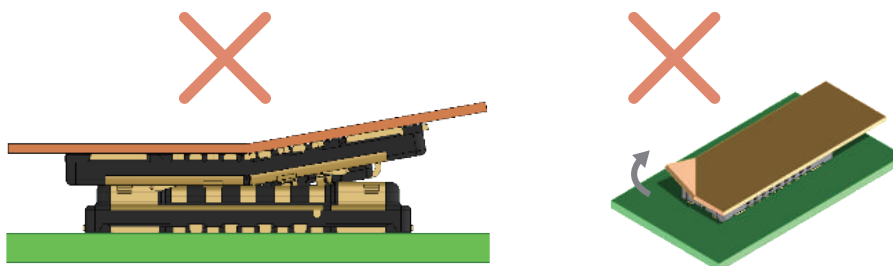
- When removing the connector, it is preferable to pull it out in the upward direction from the connector mounting surface.
However, when removing the FPC from the circuit board it becomes more difficult to remove it vertically with higher pin counts and thin FPCs.



- If difficult to remove, extract the connector diagonally in the direction of the pitch.
Note that removal from the widthwise side will apply a large load to the contacts.
When removing from the width direction, pull the end of the FPC in the upward direction.
(When a force is applied in the horizontal direction, a large load is applied to the contact.)



- If the FPC does not have sufficient rigidity, solder stripping or connector breakage may occur.
Please use it after checking the repetitive operation with a flexible board in advance, such as during a trial manufacture run.
Refrain from holding the corner of the flexible board and removing it diagonally as it will result in a large load to the contacts.



While Taking into Consideration

Specifications mentioned in this catalog are reference values.
When considering to order or use this product, please confirm the Drawing and Product Specifications sheets.
Use an appropriate cable when using the connector in combination with cables.
If considering usage of a non-specified cable, please contact your sales representative.
If assembly process is done by jigs & tools which are not identified by Hirose, assurance will not be given.
If considering usage for below mentioned applications, please contact your sales representative.
In cases where the application will demand a high level of reliability, such as automotive, medical instruments, public infrastructure, aerospace/ defense etc. Hirose must review before assurance of reliability can be given.

HIROSE